

Intel Corporation
2200 Mission College Blvd.
P.O. Box 58119
Santa Clara, CA 95052-8119



News Release

CONTACT: Heather Clisby
415-385-7448
heather.clisby@bm.com

INTEL ANNOUNCES SINGLE CHIP CMOS PCI-E UWB SILICON AND FORM-FACTOR MODULE DESIGNS

HMC form-factor design with 6-7.9 Ghz BG3 support

LAS VEGAS, Jan. 3, 2008 – Intel Corporation, through its Ultrawideband Networking Operation, today announced the availability of the “Intel® Wireless UWB Link 3480” Single Chip CMOS UWB silicon samples and form-factor UWB host solutions. Intel’s second generation UWB solutions, based on the Certified Wireless USB* Specification from the USB-IF and the WLP Specification from the WiMedia Alliance, will enable PC OEMs to offer integrated UWB modules that are optimized for higher throughput and lower power consumption in comparison to the first generation of UWB products based on the USB2.0 interface. These new wireless solutions will provide personal area connectivity in the digital home and office.

“By delivering the industry’s first single chip PCI-E solution, Intel continues to take a leadership role in providing UWB host solutions for IHVs and PC OEMs,” said Jose Avalos, General Manager of Intel's Ultra-wideband Networking Operation. “Our second generation solution follows the success of our first generation solution that enabled the first Certified Wireless USB product to ship in Retail.”

Intel’s second generation silicon includes UWB MAC, Baseband and RF sub-systems integrated into a single die in a 10x10mm 72 pin QFN package. “Modules based on Intel’s single chip PCI-E* UWB solution will enable wireless sync-and-go applications with higher throughput at lower power, which will drive UWB notebook PC integration and a better end-user

experience”, said Brian O’Rourke, principal analyst at In-Stat. PCI-E interface enables more optimized system level power management which is key for integrating UWB modules into notebook PCs. This single chip supports BG1 and BG3 (6-7.9 Ghz) solutions, thereby making shipment of this product possible to multiple geographies world-wide.

“Intel is one of the leading companies providing WiMedia UWB based solutions that have enabled some of the first Wireless USB consumer products,” said Jeff Ravencraft, USB-IF president. “This second generation solution offers two key ingredients, higher performance and improved system integration, which will enable an ever growing eco-system and bring more Wireless USB devices to market quickly.”

The Intel host solution is designed for concurrent operation of Certified Wireless USB and WLP and is expected to interoperate with multiple device peripherals such as Wireless USB Hubs, cameras and printers.

Certified Wireless USB technology enables wireless access up to 480 megabits-per-second within three meters or 110 megabits-per-second within ten meters. Using Certified Wireless USB technology, PCs, Portable CE and mobile devices can download or transfer huge files quickly with high-energy efficiency and without the hindrance of cables.

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